

Docket No.: M4065.0468/P468-B  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Phillip E. Byrd, et al.

Application No.: NOT YET ASSIGNED

Art Unit: N/A

Filed: Concurrently Herewith

Examiner: Not Yet Assigned

For: **METHOD FOR TEMPORARILY  
ISOLATING A DIE FROM A COMMON  
CONDUCTOR TO FACILITATE WAFER  
LEVEL TESTING (AS AMENDED)**

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**FIRST PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 6 of this paper.

**Remarks/Arguments** begin on page 11 of this paper.